ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	PC. Bannock	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the encompass	substances ses all low	s within the er level ma	manufacture terials for wh	er listed ite nich the ma	m. Note: i nufacture	if the item is an as r has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi	emi										2024-05-11			
Contact Name	t Name Title - Contact					Phone - Contact*					Email - Contact*			
Product-Env-Stewards Product Enviro Con			o Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*					Email - Representative*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Da	e Versio	Version Manufacturing Site		ring Site	W	eight*	UOM	Unit Type
	NCP114	VCP114ASN080T1G 300 mA CMOS LI Vout=0.8V		LDO, AD option	1,	2024-05-11			CN1		13	.65	mg	Each
Manufacturing Proccess Informa	tion													
Terminal Plating / Grid Array Ma	ay Material Terminal Base Alloy		Alloy	J-STD-020 MSI	L Rating	Peak Pro	Process Body Temperature Max Time at Peal		ime at Peak '	Temperature Number of Ref		ber of Reflow Cyd	les	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		second	3			
Comments														
evel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds											
for more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.526	mg
			В	Nickel (Ni)	7440-02-0		2.127	mg
			Supplier	Iron (Fe)	7439-89-6		2.9189	mg
			Supplier	Copper (Cu)	7440-50-8		0.2081	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg